



Huawei Ascend 910A

Da Vinci OAM 2019 TSMC 7nm

OVERVIEW

16.0 FP32 TFLOPS	32 GB VRAM HBM2	1.2 TB/s Memory Bandwidth	310 W TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
INT8	512.0	8	Standard
FP16	256.0	16	Standard
FP32	16.0	32	Standard

MEMORY SPECIFICATIONS

Capacity	32 GB
Type	HBM2
Bandwidth	1.2 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	310 W
Est. Max Power	357 W
FP32 Efficiency	0.05 TFLOPS/W
FP16 Efficiency	0.83 TFLOPS/W

HARDWARE DETAILS

Vendor: Huawei	Architecture: Da Vinci	Process Node: TSMC 7nm
Form Factor: OAM	Launch Year: 2019	

INTERCONNECT

GPU-to-GPU: HCCS	Bandwidth: 90 GB/s
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